

IN THE ABSTRACT:

Please delete the Abstract as originally filed in the International Application, including the "Title" and "[Figure 1]" designation on that same page, and substitute therefor the following:

The present invention relates to a method for electroless deposition of a metal layer on selected portions of a substrate. A preferred form of the invention relates to a method of depositing a desired metal layer, by electroless deposition, on one or more selected portions of an indium tin oxide (ITO) surface of a substrate. These selected portions are typically transparent conductive paths of ITO. The method includes a number of steps. ~~The first step involves~~ including applying a masking layer onto the surface, the masking layer ~~has~~ having one or more apertures formed therein so as to expose the one or more selected portions of the surface. ~~The next step involves~~: exposing the one or more selected portions of the surface to a colloidal suspension of catalytic particles adapted to adsorb to the substrate surface and to enhance deposition of the desired metal layer ~~thereon~~. ~~The next step involves~~ , and exposing the one or more selected portions of the surface to an ionic solution containing ions of the desired metal to enable formation of the metal layer.